

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:) Before the Examiner
Michael T. Meyer)
Serial No. 10/635,101) Group Art Unit
Filed: August 6, 2003)
APPARATUS FOR HEAT TRANSFER)
AND CRITICAL HEAT FLUX)
ENHANCEMENT) October 6, 2003

INFORMATION DISCLOSURE STATEMENT

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Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure embodied in 37 CFR §1.56, Applicant wishes to formally bring to the attention of the Examiner the following patents, publications and/or other information:

The references are listed on the attached Form 1449.

Copies of cited items are enclosed herewith.

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October 6, 2003
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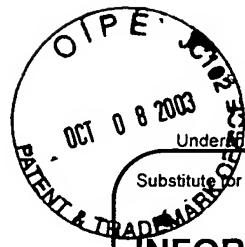
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Respectfully submitted

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| Application Number | 10/635,101 |
| Filing Date | August 6, 2003 |
| First Named Inventor | Michael T. Meyer |
| Art Unit | |
| Examiner Name | |

Attorney Docket Number

16380-4

NON PATENT LITERATURE DOCUMENTS

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| | | BOWERS, M.B. et al., High flux boiling in low flow rate, low pressure mini-channel and micro-channel heat sinks. Int. J. Heat Mass Transfer, Vol. 37, No. 2, pp.321-332, 1994, Great Britain. | |
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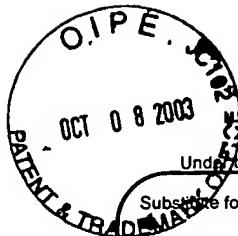
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| | | Maddox, D.E. et al., Single- and Two-Phase Convective Heat Transfer from Smooth and Enhanced Microelectric Heat Sources in a Rectangular Channel. Journal of Heat Transfer, Vol. 111, pp. 1045-1052, November 1989. | / |
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